

NOTES: UNLESS OTHERWISE SPECIFIED.

1. FABRICATE PER IPC-6012A CLASS 2.

DIELECTRIC: FR4ISOLA\_FR408HR/FR4\_ITEQ IT168G.

COPPER: AS PER STACKUP.

U.L. RATING: 94V-0 MINIMUM

3. SURFACE FINISH: ENIG

4. SOLDER MASK MATERIAL SHALL MEET ALL THE REQUIREMENTS OF IPC-SM-840C AND SHALL BE GREEN IN COLOR AND APPLIED OVER BARE COPPER.

5. SILK SCREEN LEGEND TO BE APPLIED PER LAYER STACKUP USING WHITE NON-CONDUCTIVE EPOXY INK.

6. 100% CONTINUITY TESTING USING DATABASE NETLIST SHALL BE PERFORMED, VENDOR TO IDENTIFY TEST PASSED IN SECONDARY SIDE.

7. VENDOR TO MARK DATE CODE AND LOGO IN ETCH OR IN LEGEND.

8. BOW AND TWIST SHALL NOT EXCEED 0.7% OF LONGEST SIDE .

9. DIELECTRICS AND LINewidthS MAY BE ADJUSTED TO MEET THE IMPEDANCE REQUIREMENTS.

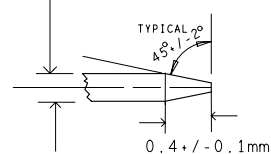
10. MINIMUM CONDUCTOR WIDTH:3.5 MILS

MINIMUM SPACING:4.0 MILS

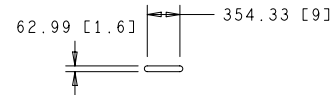
11. THE PCB EDGE NEAR AMC CONNECTOR EDGE SHOULD BE AS SHOWN IN THE BELOW FIG.

SCALE: NONE

62.8Mil [1.59MM]  
PCB THICKNESS



12. NONPLATED SLOT DETAILS AS SHOWN BELOW FIG.



SINGLE ENDED IMPEDANCE

LAYER NO	CONDUCTOR WIDTH	REFERENCE LAYER	IMPEDANCE +/- 10%
1 & 12	5.0 MIL	2 & 11	50 OHMS
3 & 10	4.0 MIL	2 & 11	50 OHMS
5	4.5 MIL	6	50 OHMS
8	4.5 MIL	7	50 OHMS

DIFFERENTIAL IMPEDANCE

LAYER NO	CONDUCTOR WIDTH	SPACING	REFERENCE LAYER	IMPEDANCE +/- 10%
1 & 12	7.0 MIL	10.0MIL	2 & 11	90 OHMS
1 & 12	4.0 MIL	6.0 MIL	2 & 11	100 OHMS
3 & 10	3.5 MIL	5.0 MIL	2 & 11	100 OHMS
5 & 8	4.0 MIL	6.0 MIL	6 & 7	100 OHMS

12-LAYER STACK BUILD

-----	PRIMARY SIDE, SILK SCREEN	
-----	PRIMARY SIDE, SOLDER MASK	
-----	PRIMARY SIDE, LAYER 1	----->2.10 Mils(1.0 OZ)
-----	PREPREG-Er(3.9)	----->3.60 Mils
-----	GROUND1, LAYER 2	----->1.20 Mils(1.0 OZ)
-----	CORE-Er(3.9)	----->4.00 Mils
-----	INNER LAYER, LAYER 3	----->0.60 Mils(0.5 OZ)
-----	PREPREG-Er(3.85)	----->4.80 Mils
-----	POWER1, LAYER 4	----->1.20 Mils(1.0 OZ)
-----	CORE-Er(3.9)	----->5.00 Mils
-----	INNER LAYER, LAYER 5	----->0.60 Mils(0.5 OZ)
-----	PREPREG-Er(3.9)	----->4.40 Mils
-----	GROUND2, LAYER 6	----->1.20 Mils(1.0 OZ)
-----	CORE-Er(3.9)	----->4.00 Mils
-----	GROUND3, LAYER 7	----->1.20 Mils(1.0 OZ)
-----	PREPREG-Er(3.9)	----->4.40 Mils
-----	INNER LAYER, LAYER 8	----->0.60 Mils(0.5 OZ)
-----	CORE-Er(3.9)	----->5.00 Mils
-----	POWER2, LAYER 9	----->1.20 Mils(1.0 OZ)
-----	PREPREG-Er(3.85)	----->4.80 Mils
-----	INNER LAYER, LAYER 10	----->0.60 Mils(0.5 OZ)
-----	CORE-Er(3.9)	----->4.00 Mils
-----	GROUND4, LAYER 11	----->1.20 Mils(1.0 OZ)
-----	PREPREG-Er(3.9)	----->3.60 Mils
-----	SECONDARY SIDE, LAYER 12	----->2.10 Mils(1.0 OZ)
-----	SECONDARY SIDE, SOLDER MASK	
-----	SECONDARY SIDE, SILK SCREEN	

61.40 Mils+/-10%



CAUTION  
SENSITIVE ELECTRONIC DEVICES-CLASS 1

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
A	8.0	+3.0/-3.0	PLATED	526
B	10.0	+3.0/-3.0	PLATED	2109
C	14.0	+3.0/-3.0	PLATED	4
D	15.0	+3.0/-3.0	PLATED	169
E	28.0	+3.0/-3.0	PLATED	5
F	35.0	+3.0/-3.0	PLATED	12
G	38.0	+3.0/-3.0	PLATED	7
H	40.0	+3.0/-3.0	PLATED	18
I	42.0	+3.0/-3.0	PLATED	2
J	45.0	+3.0/-3.0	PLATED	16
K	47.0	+3.0/-3.0	PLATED	1
L	50.0	+3.0/-3.0	PLATED	5
M	51.0	+3.0/-3.0	PLATED	6
N	53.0	+3.0/-3.0	PLATED	1
O	62.0	+3.0/-3.0	PLATED	2
P	87.0	+3.0/-3.0	PLATED	2
Q	106.0	+3.0/-3.0	PLATED	2
R	125.0	+3.0/-3.0	PLATED	8
*	51.0	+2.0/-2.0	NON-PLATED	2
+	64.0	+2.0/-2.0	NON-PLATED	2
+	130.0	+2.0/-2.0	NON-PLATED	2
-	138.0	+2.0/-2.0	NON-PLATED	4
=	75.0x28.0	+3.0/-3.0	PLATED	2
B	30.0x120.0	+3.0/-3.0	PLATED	1
=	120.0x30.0	+3.0/-3.0	PLATED	1
=	140.0x40.0	+3.0/-3.0	PLATED	1

COMPANY NAME :eINFOCHIPS LIMITED  
DATE:MAY 06,2012 JOB NUMBER:EINF4567A  
DESIGNED BY:eINFOCHIPS LIMITED  
PART NO/CARD REF: TMDSEVM6657 REV -02  
FILM LAYER:FABRICATION DRAWING

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		eINFOCHIPS LIMITED	
		FABRICATION DRAWING TMDSEVM6657	
DATE MAY06,2012		SIZE B	REV 02
SCALE 1/1		SHEET 1 OF 1	

CAD DATA 2 DO NOT MANUALLY 1 UPDATE